

Silicon N-Channel Power MOSFET

Description

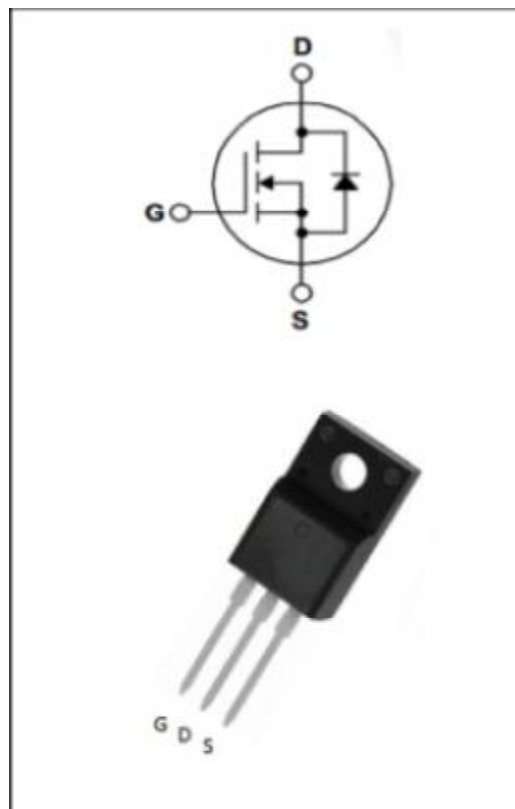
The MPF13N50 uses advanced technology and design to provide excellent $R_{DS(ON)}$. It can be used in a wide variety of applications.

General Features

- $V_{DS}=500V, I_D=13A$
- Low ON Resistance
- Low Reverse transfer capacitances
- 100% Single Pulse avalanche energy Test

Application

- Power switching application
- Adapter and charger



Electrical Characteristics @ $T_a=25^{\circ}C$ (unless otherwise specified)

a) Absolute Maximum Ratings:

Symbol	Parameter	Value	Units
V_{DSS}	Drain-to-Source Breakdown Voltage	500	V
I_D	Drain Current (continuous) at $T_c=25^{\circ}C$	13	A
I_{DM}	Drain Current (pulsed)	52	A
V_{GS}	Gate to Source Voltage	+/-30	V
P_{tot}	Total Dissipation at $T_c=25^{\circ}C$	60	W
T_j	Max. Operating Junction Temperature	175	$^{\circ}C$
E_{AS}	Single Pulse Avalanche Energy	1000	mJ

b) Electrical Parameters:

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
V_{DS}	Drain-source Voltage	$V_{GS} = 0V, I_D = 250\mu A$	500			V
$R_{DS(on)}$	Static Drain-to-Source on-Resistance	$V_{GS} = 10V, I_D = 6.5A$		0.37	0.45	Ω
$V_{GS(th)}$	Gated Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250\mu A$	2.0	3.0	4.0	V
I_{DSS}	Drain to Source leakage Current	$V_{DS} = 500V, V_{GS} = 0V$			1.0	μA
$I_{GSS(F)}$	Gated to Source Forward Leakage	$V_{GS} = +30V$			100	nA
$I_{GSS(R)}$	Gated to Source Reverse Leakage	$V_{GS} = -30V$			-100	nA
C_{iss}	Input Capacitance	$V_{GS} = 0V, V_{DS} = 25V, f = 1.0MHz$		2315		pF
C_{oss}	Output Capacitance			190		pF
C_{rss}	Reverse Transfer Capacitance			11		pF

c) Switching Characteristics

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
$t_{d(on)}$	Turn-on Delay Time	$V_{DD} = 250V, I_D = 13A, R_G = 10\Omega$		28		nS
t_r	Turn-on Rise Time			21		nS
$t_{d(off)}$	Turn-off Delay Time			62		nS
t_f	Turn-off Fall Time			32		nS
Q_g	Total Gate Charge	$V_{DS} = 400V, I_D = 13A, V_{GS} = 10V$		40		nC
Q_{gs}	Gate-Source Charge			9.2		nC
Q_{gd}	Gate-Drain Charge			14		nC

d) Source-Drain Diode Characteristics

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
I_{SD}	S-D Current(Body Diode)				13	A
I_{SDM}	Pulsed S-D Current(Body Diode)				52	A
V_{SD}	Diode Forward Voltage	$V_{GS} = 0V, I_{DS} = 13A$			1.5	V
t_{rr}	Reverse Recovery Time	$T_J = 25^\circ C, I_F = 13A, di/dt = 100A/\mu s$			555	nS
Q_{rr}	Reverse Recovery Charge				4550	μC
*Pulse Test: Pulse Width $\leq 300\mu s$, Duty Cycle $\leq 2\%$						

Symbol	Parameter	Typ	Units
$R_{\theta JC}$	Junction-to-case	2.0	$^\circ C/W$

Typical Characteristics $T_J = 25^\circ\text{C}$, unless otherwise noted

Figure 1. Output Characteristics ($T_J = 25^\circ\text{C}$)

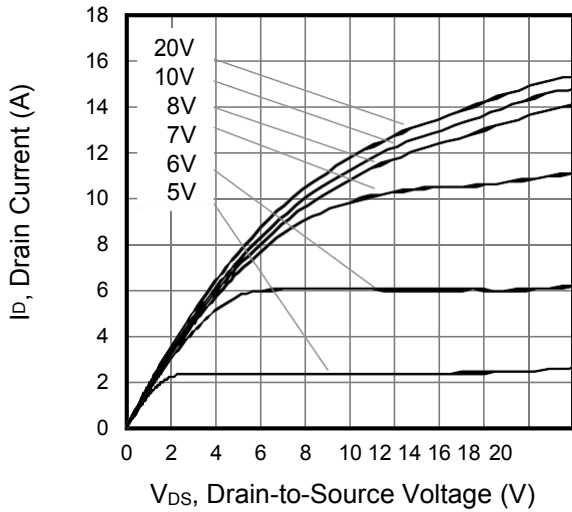


Figure 2. Body Diode Forward Voltage

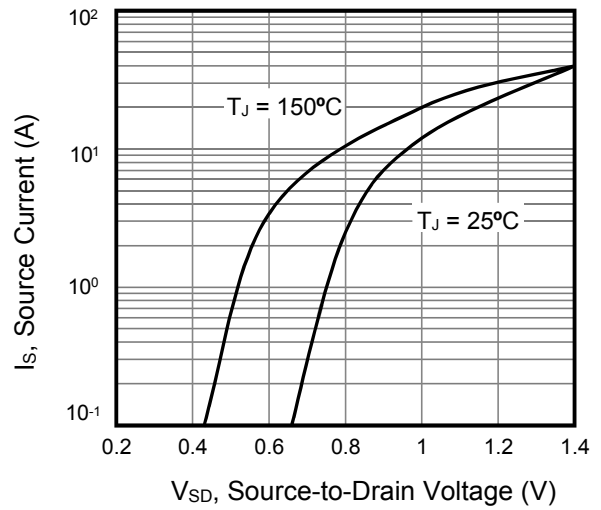


Figure 3. Drain Current vs. Temperature

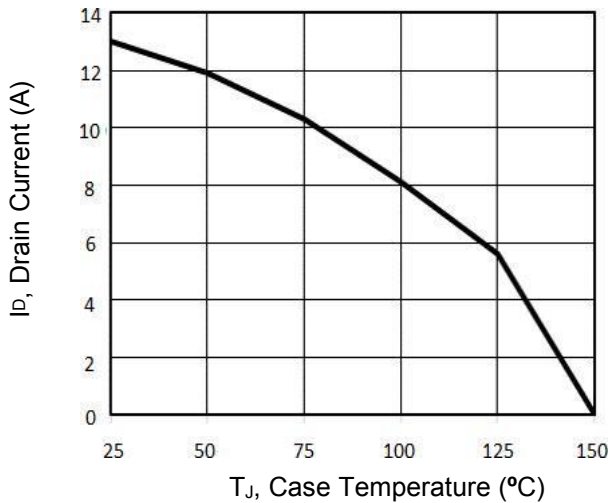


Figure 4. BV_{DSS} Variation vs. Temperature

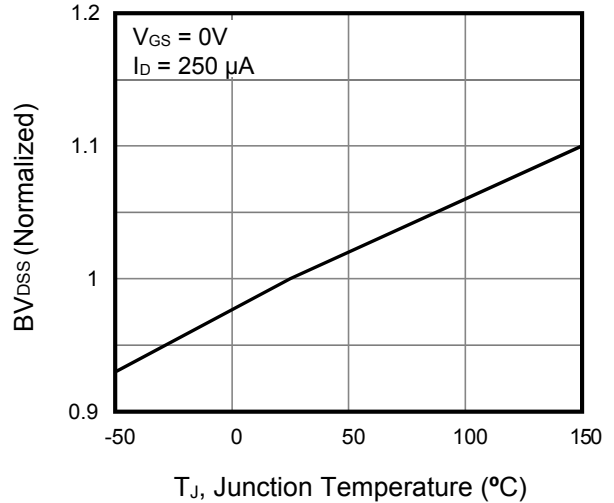


Figure 5. Transfer Characteristics

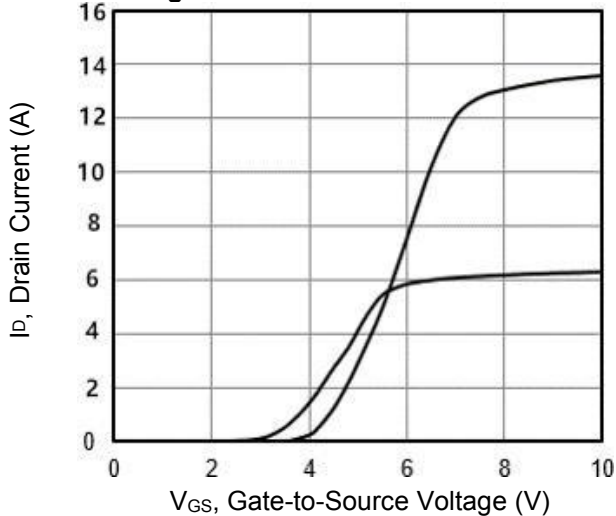
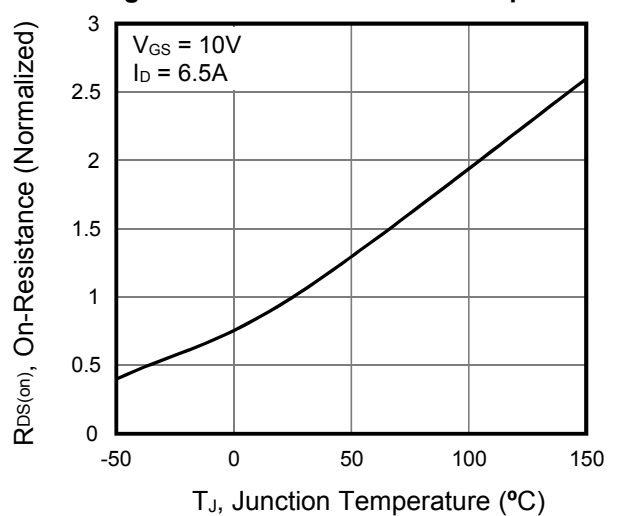


Figure 6. On-Resistance vs. Temperature



Typical Characteristics $T_J = 25^\circ\text{C}$, unless otherwise noted

Figure 7. Capacitance

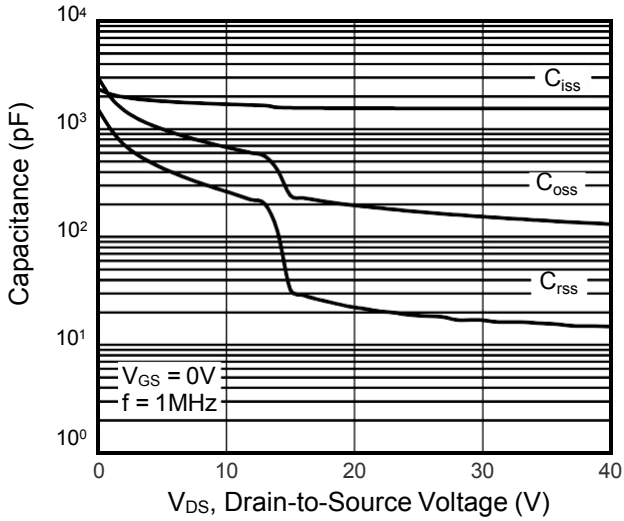


Figure 8. Gate Charge

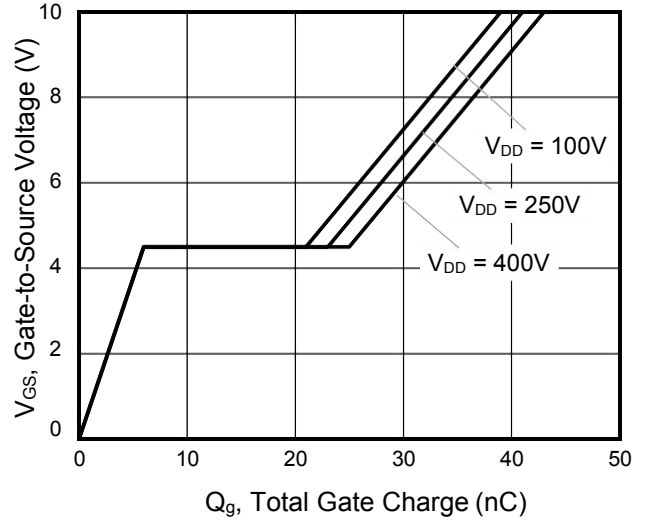


Figure 9. Transient Thermal Impedance TO-220F

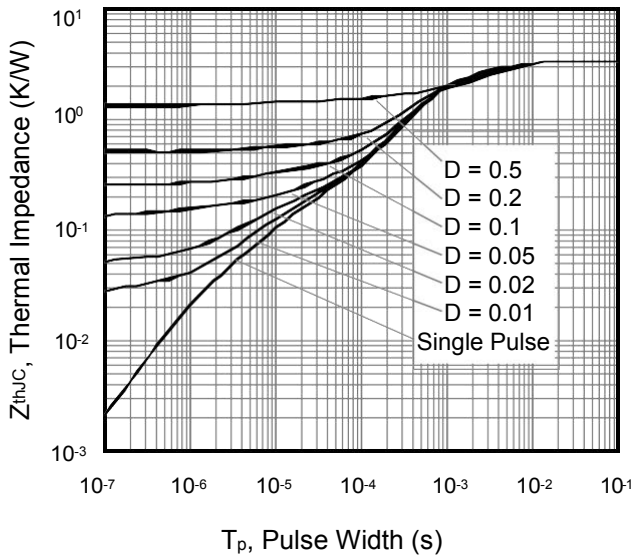
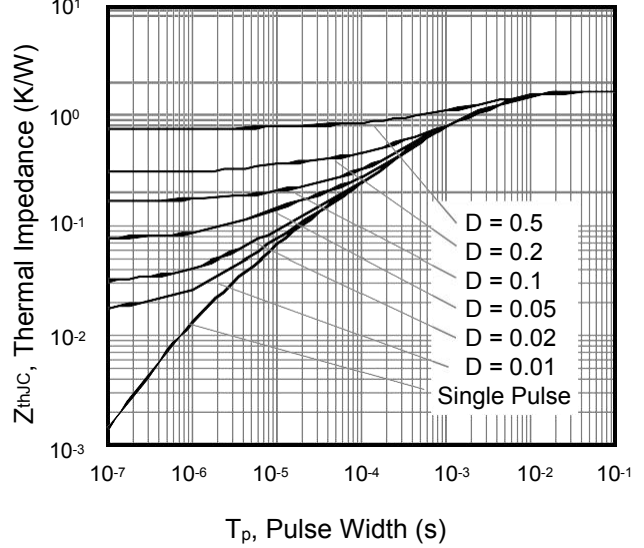
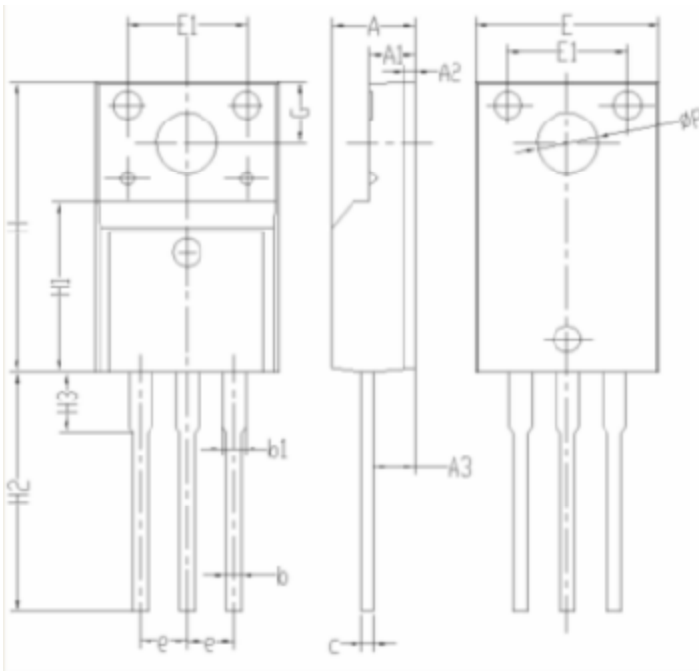


Figure 10. Transient Thermal Impedance TO-220



TO-220F PACKAGE



Symbol	Dimensions in millimeters	
	Min	Max
A	4.35	4.75
A1	2.30	2.70
A2	0.40	0.80
A3	2.10	2.50
b	0.80	1.00
b1	1.00	1.40
c	0.30	0.70
e	2.30	2.70
E	9.80	10.2
E1	6.30	6.70
H	15.6	16.0
H1	8.80	9.20
H2	12.9	13.5
H3	3.10	3.50
G	3.10	3.50
∅P	3.10	3.50